

ABSTRACT

SPUTTERING TARGET AND PRODUCTION METHOD THEREFOR

A sputtering target according to this invention comprises an alloy of Al and Sc and contains from 25 at.% to 50 at.% of Sc. The sputtering target has an oxygen content of 2000 ppm by mass or less, and a variation in Vickers hardness (Hv) of 20% or less.

(No Fig.)